



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



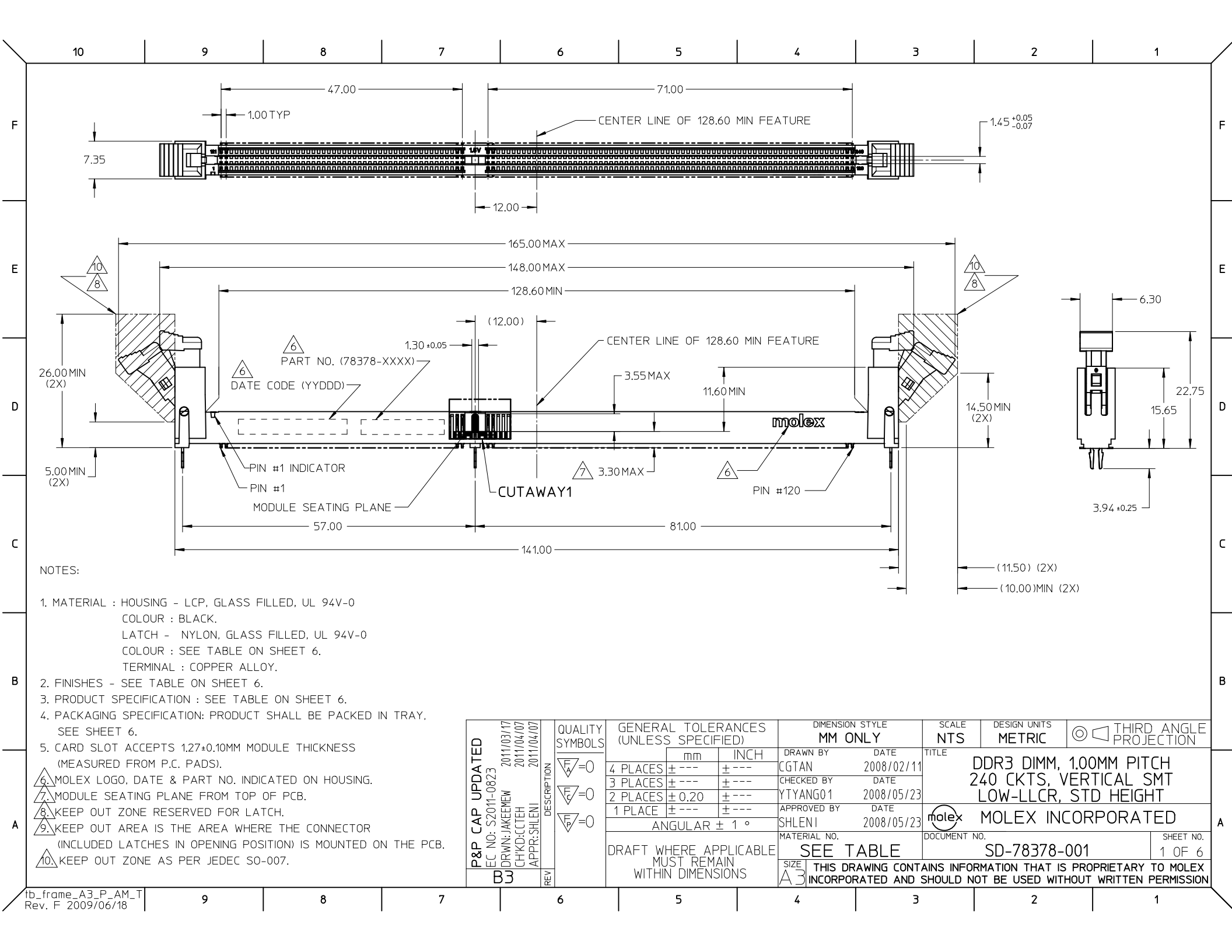
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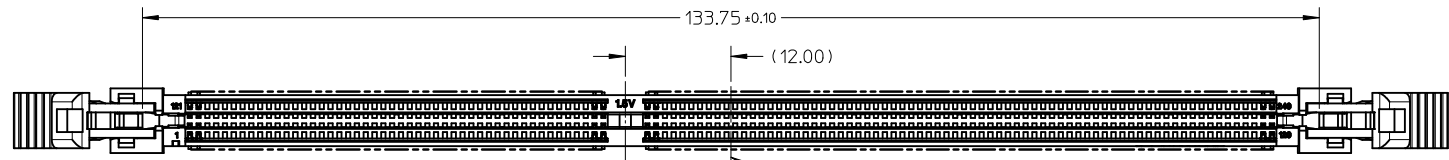


NOTES:

1. MATERIAL : HOUSING - LCP, GLASS FILLED, UL 94V-0
COLOUR : BLACK.
LATCH - NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE TABLE ON SHEET 6.
TERMINAL : COPPER ALLOY.
2. FINISHES - SEE TABLE ON SHEET 6.
3. PRODUCT SPECIFICATION : SEE TABLE ON SHEET 6.
4. PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAY,
SEE SHEET 6.
5. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS
(MEASURED FROM P.C. PADS).
6. MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
7. MODULE SEATING PLANE FROM TOP OF PCB.
8. KEEP OUT ZONE RESERVED FOR LATCH.
9. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR
(INCLUDED LATCHES IN OPENING POSITION) IS MOUNTED ON THE PCB.
10. KEEP OUT ZONE AS PER JEDEC SO-007.

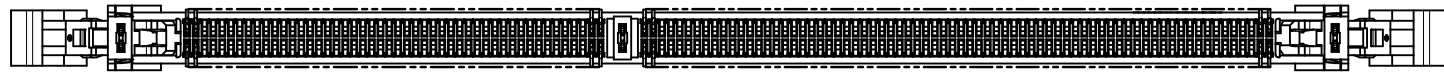
P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEEWEW CHKD: CCTEH APPR: SILENI	REV B3	DESCRIPTION 2011/03/17 2011/04/07 2011/04/07	QUALITY SYMBOLS F _A =0 F _B =0 F _C =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
						MM ONLY		NTS	METRIC		
					mm	INCH	DRAWN BY	DATE	TITLE		
				4 PLACES	± ---	± ---	CGTAN	2008/02/11	DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT		
3 PLACES	± ---	± ---	CHECKED BY	DATE	MOLEX INCORPORATED						
2 PLACES	± 0.20	± ---	YTYANG01	2008/05/23	DOCUMENT NO.						
1 PLACE	± ---	± ---	APPROVED BY	DATE	SHEET NO.						
ANGULAR ± 1 °		SHLENI		2008/05/23	SD-78378-001						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SEE TABLE		1 OF 6					
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

10 9 8 7 6 5 4 3 2 1

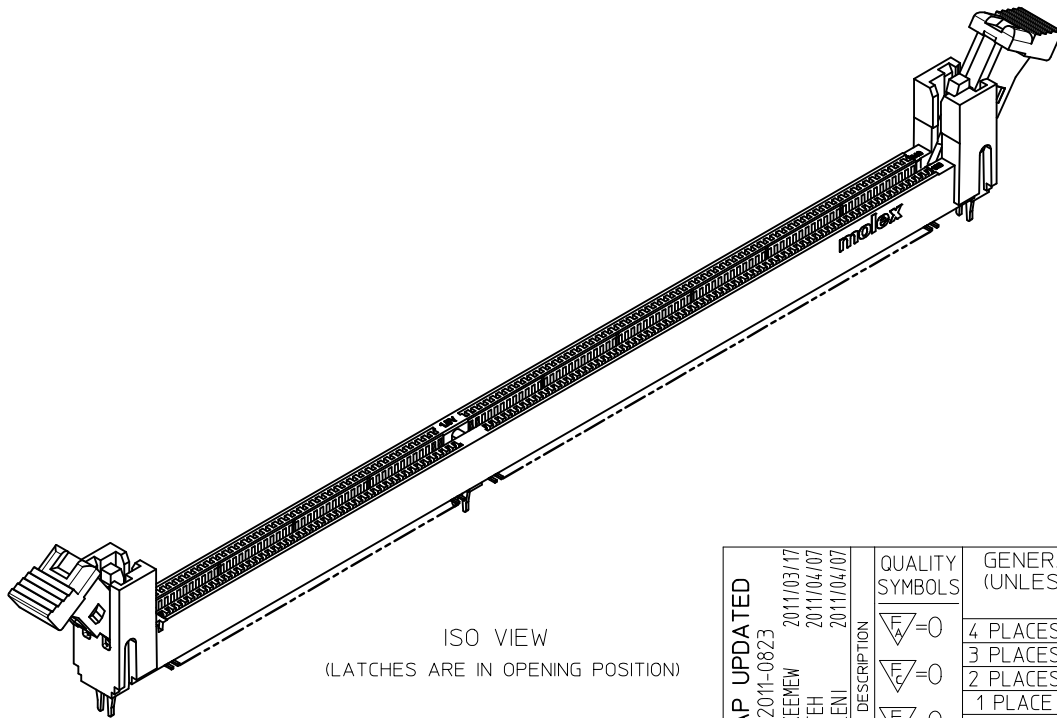


TOP VIEW
(LATCHES ARE IN OPENING POSITION)

CENTER LINE OF 128.60 MIN FEATURE



BOTTOM VIEW
(LATCHES ARE IN OPENING POSITION)

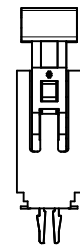
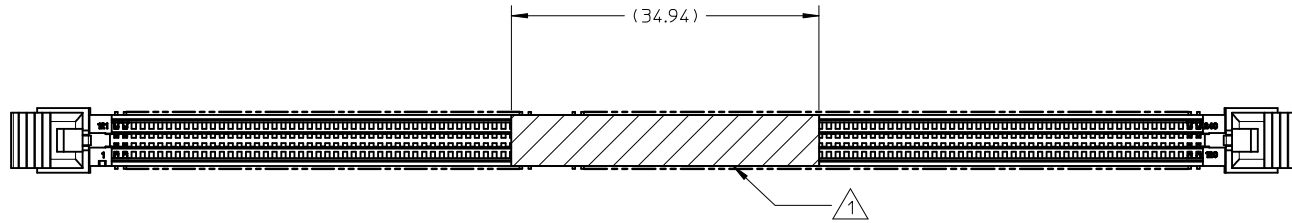


ISO VIEW
(LATCHES ARE IN OPENING POSITION)

P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEEWEW 2011/03/17 CHKD: CCTEH 2011/04/07 APPR: SHLENI 2011/04/07	DESCRIPTION REV B3	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
					DRAWN BY CGTAN	DATE 2008/02/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT			
						CHECKED BY YTYANG01	DATE 2008/05/23	MOLEX INCORPORATED		
						APPROVED BY SHLENI	DATE 2008/05/23	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78378-001	SHEET NO. 2 OF 6
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

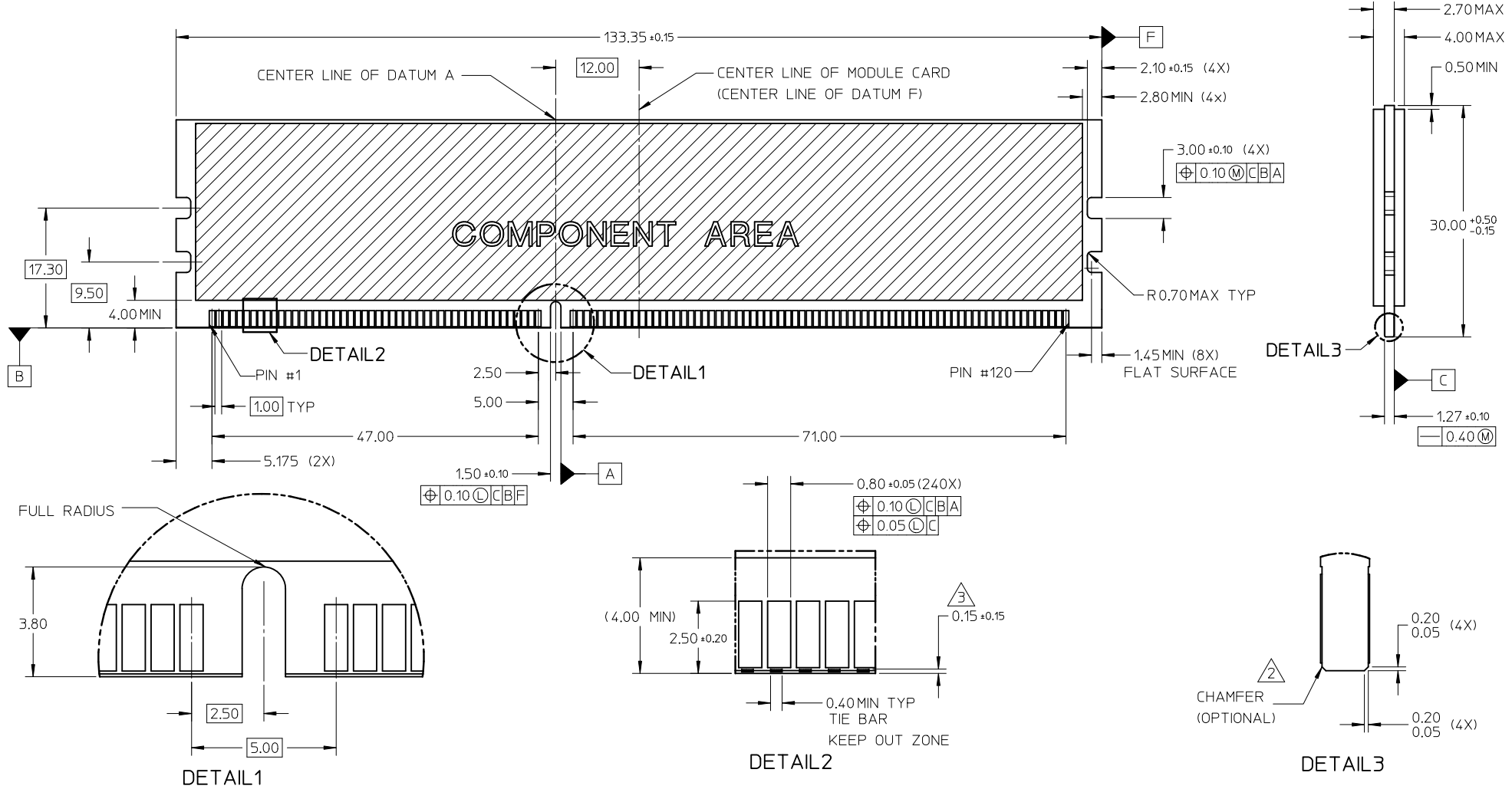
VIEWS WITH PICK & PLACE CAP



1. AREA FOR PICK AND PLACE

P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEEM 2011/03/17 CHKD: CCTH 2011/04/07 APPR: SHLENI 2011/04/07	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla_F = 0$ $\nabla_E = 0$ $\nabla_D = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	MM ONLY	NTS	METRIC	
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY	DATE	TITLE	
	REV		CGTAN	2008/02/11	DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT	
B3			CHECKED BY	DATE	MOLEX INCORPORATED	
			YTYANG01	2008/05/23	MOLEX INCORPORATED	
			APPROVED BY	DATE	DOCUMENT NO.	SHEET NO.
			SHLENI	2008/05/23	SD-78378-001	3 OF 6
			MATERIAL NO.			
			SEE TABLE			
			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			A3			

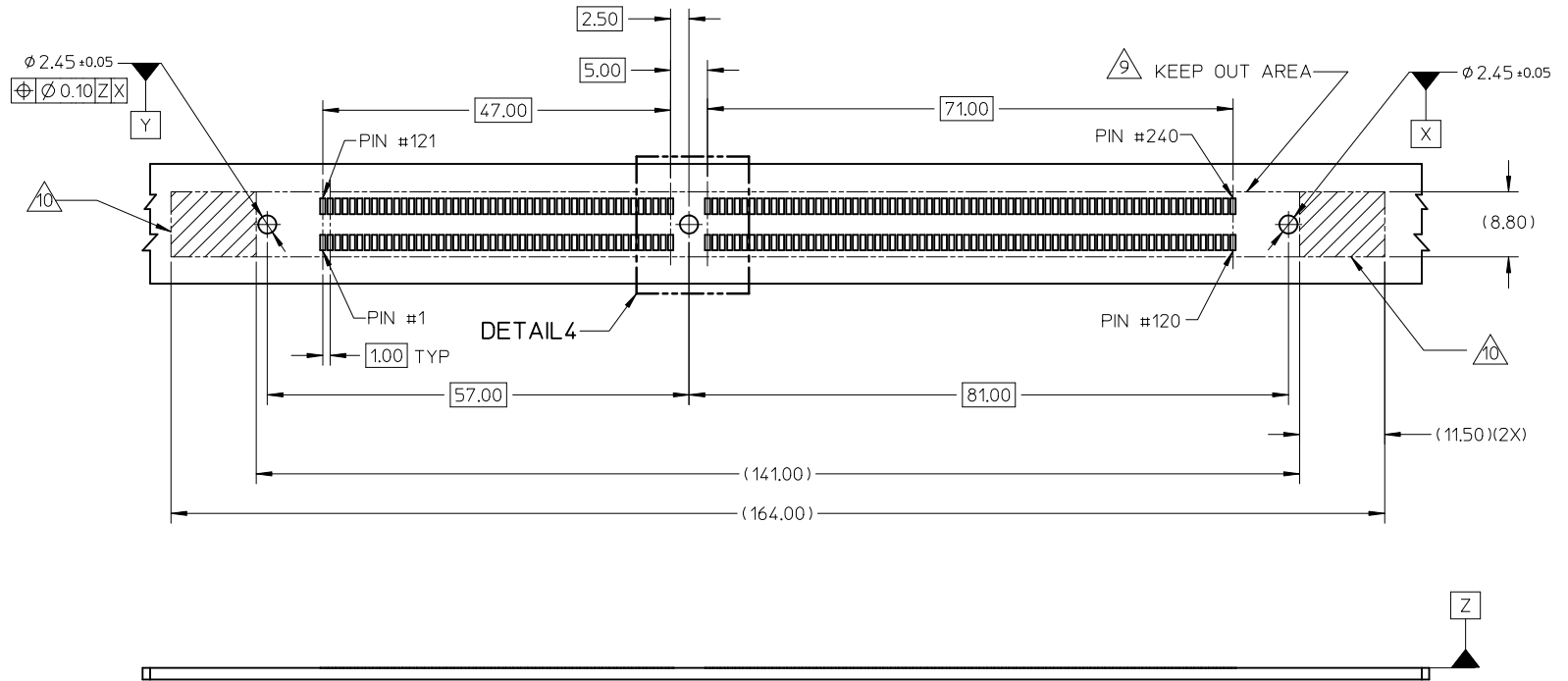
MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE B, APRIL/06)



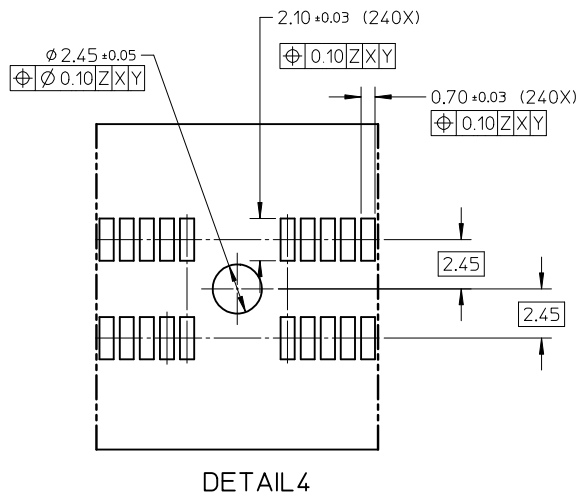
- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL.
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT.
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS.
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEEWEW 2011/03/17 CHKD: CCTEH 2011/04/07 APPR: SHLENI 2011/04/07	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_B=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION																		
		<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table>			mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± ---	± ---	DRAWN BY CGTAN		DATE 2008/02/11		TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT			
			mm	INCH																						
		4 PLACES	± ---	± ---																						
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DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY SHLENI		DATE 2008/05/23		DOCUMENT NO. SD-78378-001		SHEET NO. 4 OF 6																		

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RECOMMENDED PCB THICKNESS 1.57MM ~ 3.18MM
 RECOMMENDED STENCIL THICKNESS = 150 MICROMETERS



P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEENW 2011/03/17 CHKD: CCTEH 2011/04/07 APPR: SHLENI 2011/04/07	DESCRIPTION REV B3	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		$F_A = 0$ $F_C = 0$ $F_P = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---	DRAWN BY CGTAN	DATE 2008/02/11	TITLE		DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT MOLEX INCORPORATED DOCUMENT NO. SD-78378-001	
		ANGULAR ± 1 °		CHECKED BY YTYANG01	DATE 2008/05/23	MATERIAL NO.			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY SHLENI	DATE 2008/05/23	SEE TABLE			SHEET NO. 5 OF 6
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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PART NO.	VOLTAGE KEY POS.	PLATING OPTION	PICK & PLACE CAP	LATCH COLOR	PACKAGING SPECIFICATION	PRODUCT SPECIFICATION
78378-0001	CENTER (1.5V)	0.76µM (30µNCH) MIN. GOLD ON CONTACT. 2.54µM (100µNCH) MIN. PURE TIN ON SOLDER TAIL. 1.27µM (50µNCH) MIN. NICKEL UNDERPLATE.	NO	BLACK	PK-78378-002	PS-78378-001
78378-0002				PK-78378-001		
78378-0003				NATURAL (OFF-WHITE)	PK-78378-002	
78378-0004				PK-78378-001		
78378-0051			YES	BLACK	PK-78378-002	
78378-0052				PK-78378-001		
78378-0053				NATURAL (OFF-WHITE)	PK-78378-002	
78378-0054				PK-78378-001		
78378-0201		0.38µM (15µNCH) MIN. GOLD ON CONTACT. 2.54µM (100µNCH) MIN. PURE TIN ON SOLDER TAIL. 1.27µM (50µNCH) MIN. NICKEL UNDERPLATE.	NO	BLACK	PK-78378-002	PS-78378-002
78378-0202				PK-78378-001		
78378-0203				NATURAL (OFF-WHITE)	PK-78378-002	
78378-0204				PK-78378-001		
78378-0251			YES	BLACK	PK-78378-002	
78378-0252				PK-78378-001		
78378-0253	NATURAL (OFF-WHITE)			PK-78378-002		
78378-0254	PK-78378-001					

P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKE NEW 2011/03/17 CHKD: C C T E H 2011/04/07 APPR: S H L E N I 2011/04/07	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CGTAN	DATE 2008/02/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT			
		4 PLACES	± ---	± ---	CHECKED BY YTYANG01	DATE 2008/05/23	MOLEX INCORPORATED DOCUMENT NO. SD-78378-001 SHEET NO. 6 OF 6			
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2008/05/23				
2 PLACES	± 0.20	± ---	ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
1 PLACE	± ---	± ---	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					